

WHAT IS CLAIMED IS:

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1. A chip electronic component comprising:  
a circuit;  
an electronic component element having a lower surface  
and a pair of side surfaces; and  
a plurality of external electrodes arranged to extend  
over the lower surface and at least one of the side surfaces  
of said electronic component element and electrically  
connected to the circuit therein; wherein  
said each external electrode portion provided on the  
lower surface of the electric component element is provided  
with a narrow portion and a wide portion.
2. The chip electronic component according to claim 1,  
wherein the relationship  $L_1 < L_2 < L_3$  is satisfied, where  $L_1$  is  
the width of the external electrode portion located on said  
at least one of the side surfaces of said electric component  
element,  $L_2$  is the width of said narrow portion, and  $L_3$  is  
the width of said wide portion.
3. The chip electronic component according to claim 1,  
wherein said wide portion is substantially rectangular.
4. The chip electronic component according to claim 1,

wherein said wide portion is substantially circular.

5. The chip electronic component according to claim 1, wherein the wide portion is substantially triangular.

6. The chip electronic component according to claim 1, wherein a second wide portion is provided on the lower portion of the electronic component element.

7. The chip electronic component according to claim 1, wherein said electronic component element includes a piezoelectric resonant element.

8. The chip electronic component according to claim 7, further comprising a first case substrate bonded to at least one side surface of said piezoelectric resonant element so as not to hinder the vibration of the piezoelectric resonant element.

9. The chip electronic component according to claim 8, further comprising the second case substrate laminated on the upper surface of said piezoelectric resonant element so as not to hinder the vibration of the piezoelectric resonant element.

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10. The chip electronic component according to claim 7, wherein said electronic component element further comprises a first case member and a second case member surrounding said piezoelectric resonant element.

11. The chip electronic component according to claim 8, wherein a recess is provided in the first case substrate.

12. The chip electronic component according to claim 9, wherein a recess is provided in the second case substrate.

13. A mounting structure of a chip electronic component comprising a chip electronic component mounted on said printed circuit board via a conductive bond according to claim 1, wherein the bonded portion defined by a conductive bond is located inside of the outer periphery of the chip electronic component as seen from the top of the chip electronic component.

14. A chip electronic component comprising:  
a circuit;  
an electronic component element having a lower surface and a pair of side surfaces; and  
a plurality of external electrodes arranged so as to extend over the lower surface and at least one of the side

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surfaces of said electronic component element and electrically connected to the circuit therein;

wherein each external electrode portion on the lower surface of the electronic component element is arranged to have an almost uniform width from one longitudinal end to the other, and satisfies the relation  $L_1 < L_3$ , where  $L_3$  is the width of the external electrode portion on the lower surface of the electronic component element, and  $L_1$  is the width of the external electrode portion formed on the side surface of the electronic component element.

15. The chip electronic component according to claim 14, wherein said electronic component element includes a piezoelectric resonant element.

16. The chip electronic component according to claim 15, further comprising a first case substrate bonded to at least one side surface of said piezoelectric resonant element so as not to hinder the vibration of the piezoelectric resonant element.

17. The chip electronic component according to claim 16, further comprising the second case substrate laminated on the upper surface of said piezoelectric resonant element so as not to hinder the vibration of the piezoelectric

resonant element.

18. The chip electronic component according to claim 15, wherein said electronic component element further comprises a first case member and a second case member surrounding said piezoelectric resonant element.

19. A mounting structure of a chip electronic component comprising a chip electronic component mounted on said printed circuit board via a conductive bond according to claim 14, wherein the bonded portion defined by the conductive bond is located inside of the outer periphery of the chip electronic component as seen from the top of the chip electronic component.

20. The chip electronic component according to claim 16, wherein a recess is provided in the first case substrate.

21. The chip electronic component according to claim 17, wherein a recess is provided in the second case substrate.